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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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SD57030

RF power transistor the LdmoST family

Features

- Excellent thermal stability
- Common source configuration
- P_{OUT} = 30W with 13dB gain @ 945MHz
- BeO free package
- Internal input matching
- In compliance with the 2002/95/EC european directive

Description

The SD57030 is a common source N-channel enhancement-mode lateral Field-Effect RF power transistor designed for broadband commercial and industrial applications at frequencies up to 1.0 GHz. The SD57030 is designed for high gain and broadband performance operating in common source mode at 28 V. It is ideal for base station applications requiring high linearity.

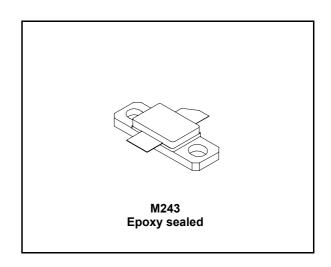


Figure 1. Pin connection

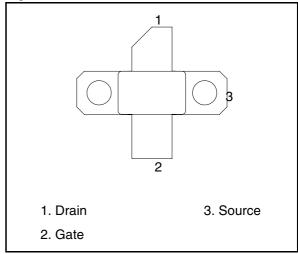


Table 1. Device summary

Order code	Package	Branding
SD57030	M243	SD57030

Contents SD57030

Contents

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SD57030 Electrical data

1 Electrical data

1.1 Maximum ratings

Table 1. Absolute maximum ratings $(T_{CASE} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit
V _{(BR)DSS}	Drain-Source voltage	65	V
V _{DGR}	Drain-Gate voltage ($R_{GS} = 1 M\Omega$)	65	V
V _{GS}	Gate-Source voltage	+ 20	V
I _D	Drain current	4	Α
P _{DISS}	Power dissipation (@ Tc = 70°C)	74	W
Tj	Max. operating junction temperature	200	°C
T _{STG}	Storage temperature	-65 to + 200	°C

1.2 Thermal data

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Junction - case thermal resistance	1.75	°C/W

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Electrical characteristics SD57030

2 Electrical characteristics

$$T_{CASE} = +25$$
 °C

2.1 Static

Table 3. Static (per section)

Symbol	Test conditions				Тур	Max	Unit
V _{(BR)DSS}	$V_{GS} = 0 V$	$I_{DS} = 10 \text{ mA}$		65			V
I _{DSS}	V _{GS} = 0 V	V _{DS} = 28 V				1	μΑ
I _{GSS}	V _{GS} = 20 V	$V_{DS} = 0 V$				1	μΑ
V _{GS(Q)}	V _{DS} = 28 V	$I_D = 50 \text{ mA}$		2.0		5.0	V
V _{DS(ON)}	V _{GS} = 10 V	$I_D = 3 A$			1.3		V
G _{FS}	V _{DS} = 10 V	I _D = 3 A			1.8		mho
C _{ISS} ⁽¹⁾	V _{GS} = 0 V	$V_{DS} = 28 \text{ V}$	f = 1 MHz		58		pF
Coss	V _{GS} = 0 V	$V_{DS} = 28 \text{ V}$	V _{DS} = 28 V f = 1 MHz		34		pF
C _{RSS}	V _{GS} = 0 V	V _{DS} = 28 V	f = 1 MHz		2.7		pF

^{1.} Includes Internal Input Moscap.

2.2 Dynamic

Table 4. Dynamic

Symbol	Test conditions	Min	Тур	Max	Unit
P _{OUT}	$V_{DD} = 28 \text{ V}$ $I_{DQ} = 50 \text{ mA}$ $f = 945 \text{ MHz}$	30			W
G _{PS}	$V_{DD} = 28 \text{ V}$ $I_{DQ} = 50 \text{ mA } P_{OUT} = 30 \text{ W}$ $f = 945 \text{ MHz}$	13	15		dB
h _D	V_{DD} = 28 V I_{DQ} = 50 mA P_{OUT} = 30 W f = 945 MHz	50	60		%
Load mismatch	$V_{DD} = 28~V~~I_{DQ} = 50~mA~~P_{OUT} = 28~W~~f = 945~MHz$ All phase angles	10:1			VSWR

70

60 🕏

10 g

0

40

f= 945 MHz

ldq= 50 mA

35

3 Typical performance (CW)

Figure 2. Output power vs input power

Figure 3. Power gain and efficiency vs output power

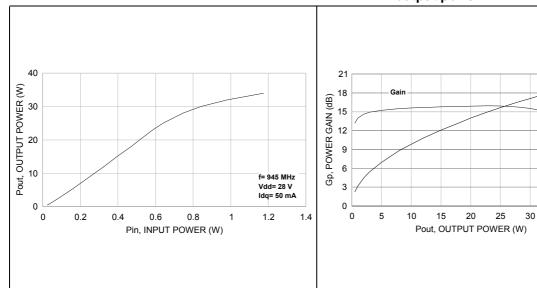
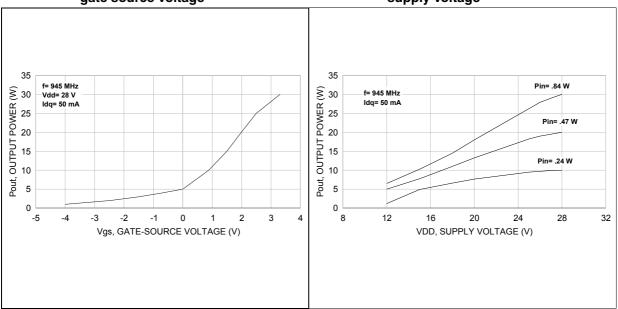


Figure 4. Output power vs gate source voltage

Figure 5. Output power vs supply voltage

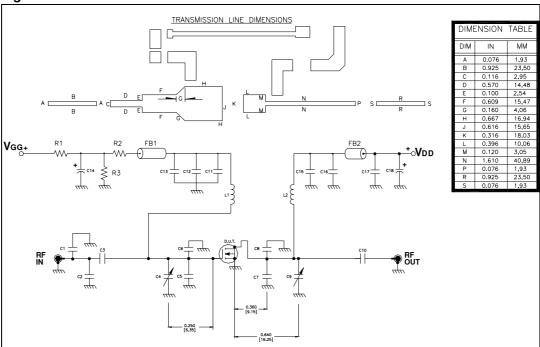


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Test circuit SD57030

4 Test circuit

Figure 6. Test circuit schematic



- 1 Dimensions at component symbols are reference for component placement.
- 2 Gap between ground & transmission line = 0.056 [1.42] +0.002 [0.05] -0.000 [0.00] typ.
- 3 Dimensions of input and output component from edge of transmission lines.

SD57030 Test circuit

Table 5. Test circuit component part list

Component	Description		
C19	200 μF / 63V ALLUMINIUM ELECTROLYTIC RADIAL LEAD CAPACITOR		
C18, C14	0.1 μF / 500V SURFACE MOUNT CERAMIC CHIP CAPACITOR		
C17	100 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR		
C16, C12, C11,C1	47 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR		
C15	10 μF / 50V ALUMINIUM ELECTROLYTIC RADIAL LEAD CAPACITOR		
C13	100 pF ATC 700B SURFACE MOUNT CERAMIC CHIP CAPACITOR		
C9, C2	0.8-8.0 pF GIGA TRIM VARIABLE CAPACITOR		
C8	6.2 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR		
C7, C6, C5 ,C4	10 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR		
C3	3 pF ATC 100B SURFACE MOUNT CERAMIC CHIP CAPACITOR		
R3	120 0-IM, 2W SURFACE MOUNT CERAMIC CHIP CAPACITOR		
R2	4.7 M OHM 1W SURFACE MOUNT CERAMIC CHIP CAPACITOR		
R1	18 K OHM, 1W SURFACE MOUNT CERAMIC CHIP CAPACITOR		
FB2, FB1	SHIELD BEAD SURFACE MOUNT EMI		
L2, L1	INDUCTOR, 5 TURNS AIR WOUND #22AWG, ID=0.059[1.49], NYLON COATED MAGNET WIRE		
РСВ	WOVEN FIBERGLASS REINFORCED PTFE 0.080" THK, ϵ r=2.55, 2 Oz EDCu BOTH SIDE		

Text circuit layout SD57030

5 Text circuit layout

Figure 7. Test fixture

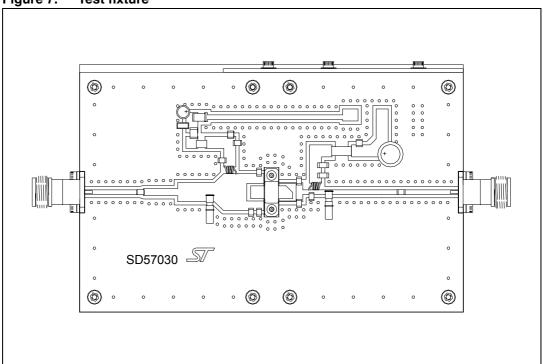
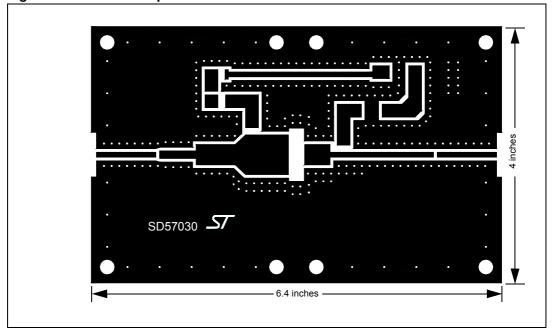


Figure 8. Test circuit photomaster

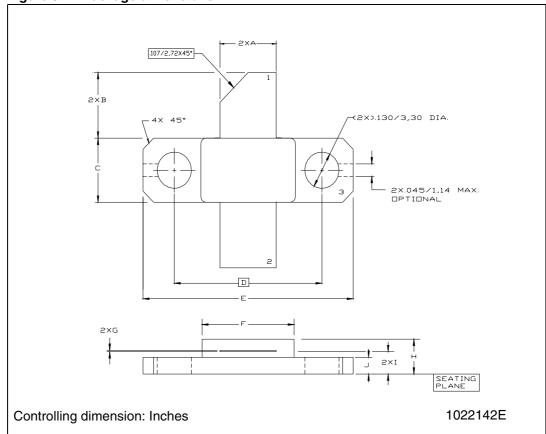


6 Package mechanical data

Table 6. M243 (.230 x .360 2L N/HERM W/FLG) mechanical data

Dim.	mm.			Inch			
	Min	Тур	Max	Min	Тур	Max	
Α	5.21		5.72	0.205		0.225	
В	5.46		6.48	0.215		0.255	
С	5.59		6.10	0.220		0.240	
D		14.27			0.562		
Е	20.07		20.57	0.790		0.810	
F	8.89		9.40	0.350		0.370	
G	0.10		0.15	0.004		0.006	
Н	3.18		4.45	0.125		0.175	
1	1.83		2.24	0.072		0.088	
J	1.27		1.78	0.050		0.070	

Figure 9. Package dimensions



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Revision history SD57030

7 Revision history

Table 7. Document revision history

Date	Revision	Changes	
24-Mar-2003	5	First Issue.	
11-Jul-2007	6 Document reformatted, added lead free info		
24-Aug-2007	7	Cover page title updated	

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